

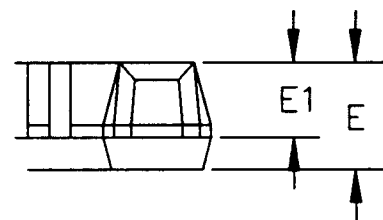
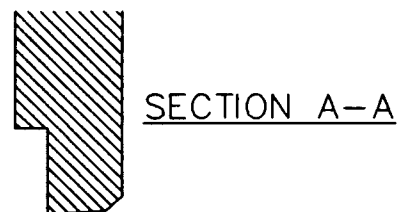
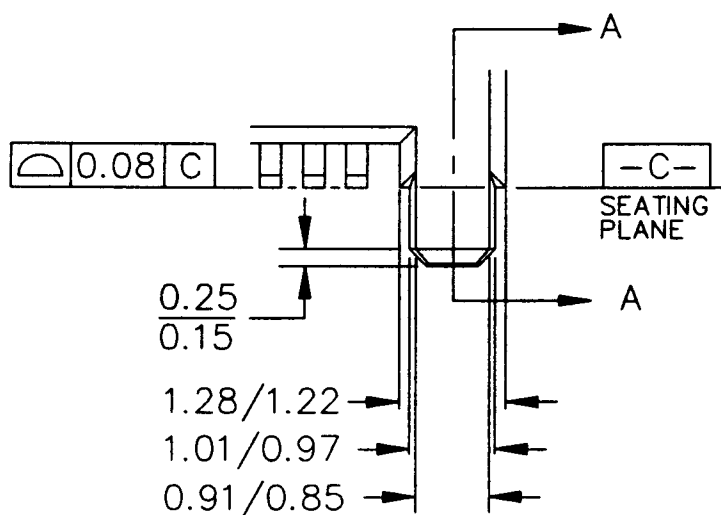
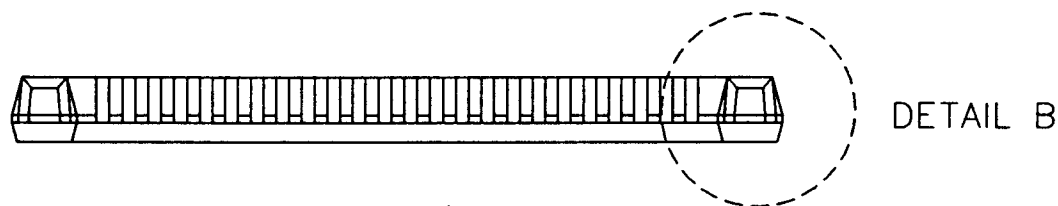
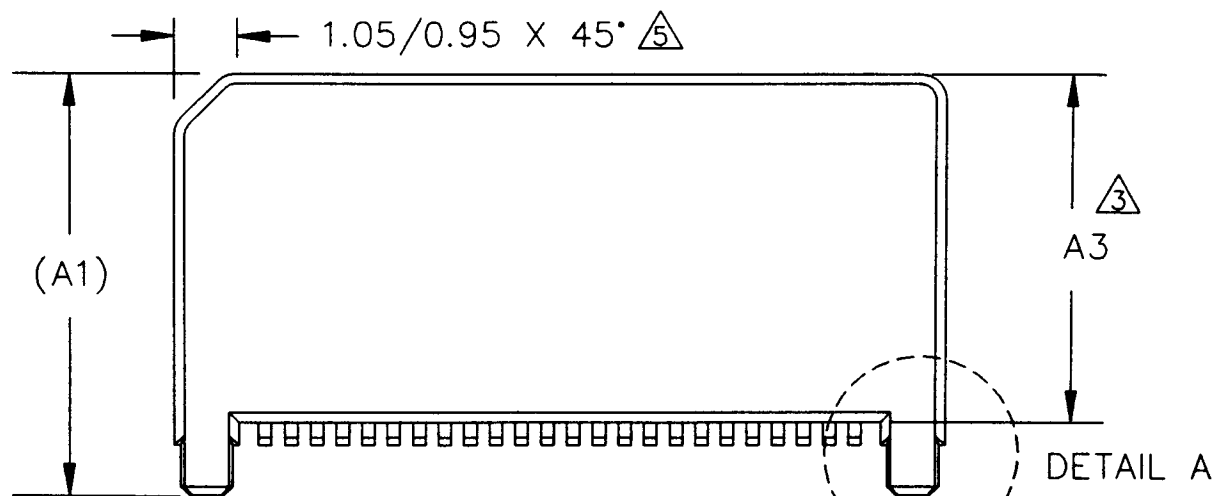
FIGURE 1

# PRINCIPAL DATUMS & DIMENSIONS

Texas Instruments Incorporation, U.S. Patent 4975763 may relate to certain features of this package outline. Licensing of this technology is available in compliance with paragraph 3.4(2) of EIA Engineering Publication EP-7A.

mm

JEDEC SOLID STATE PRODUCTS OUTLINES	TITLE VERTICAL SURFACE MOUNT PACKAGE 0.50 MM LEAD PITCH R-PSIP-X24	ISSUE A	DATE 3/93	ITEM MO - 141	SHEET 1 of 5
---	---	------------	--------------	------------------	-----------------



DETAIL A  
POST  $\Delta 6$

DETAIL B  
POST

FIGURE 2

MOLDED DETAILS

mm

JEDEC  
SOLID STATE PRODUCTS  
OUTLINES

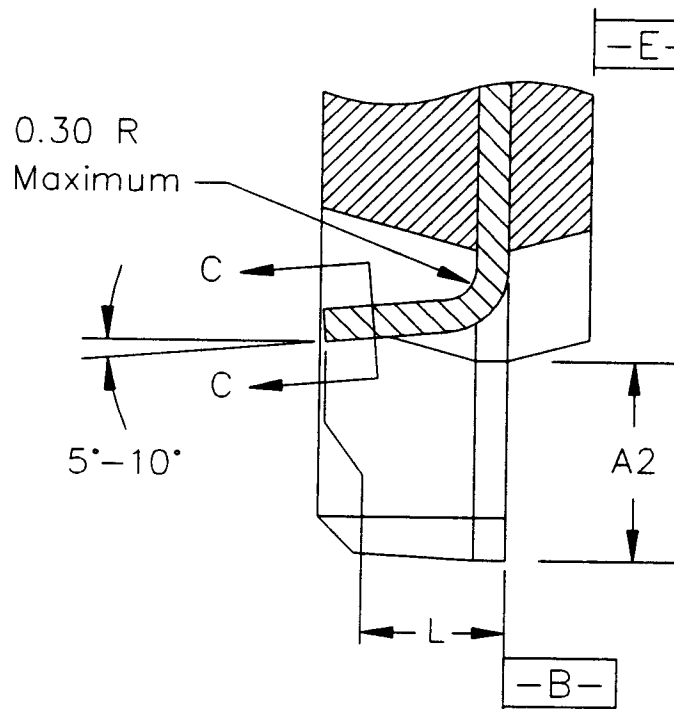
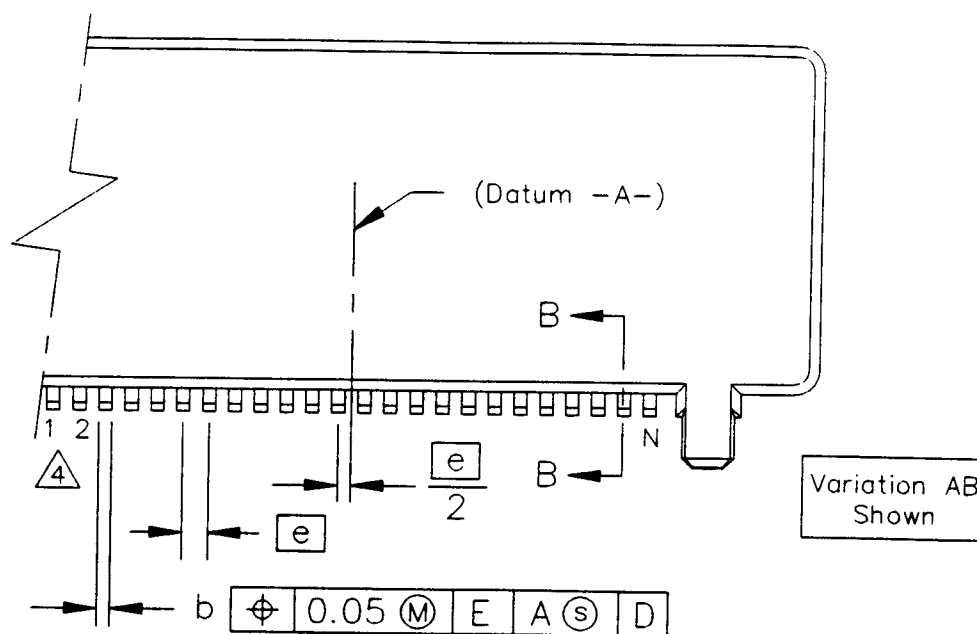
TITLE VERTICAL SURFACE  
MOUNT PACKAGE  
0.50 MM LEAD PITCH  
R-PSIP-X24

ISSUE  
A

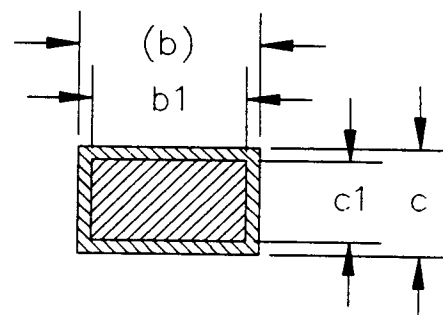
DATE  
3/93

ITEM  
MO - 141

SHEET  
2 of 5



SECTION B-B



SECTION C-C

FIGURE 3  
TERMINAL DETAILS

mm

JEDEC SOLID STATE PRODUCTS OUTLINES	TITLE VERTICAL SURFACE MOUNT PACKAGE 0.50 MM LEAD PITCH R-PSIP-X24	ISSUE A	DATE 3/93	ITEM MO - 141	SHEET 3 of 5
---	---	------------	--------------	------------------	-----------------

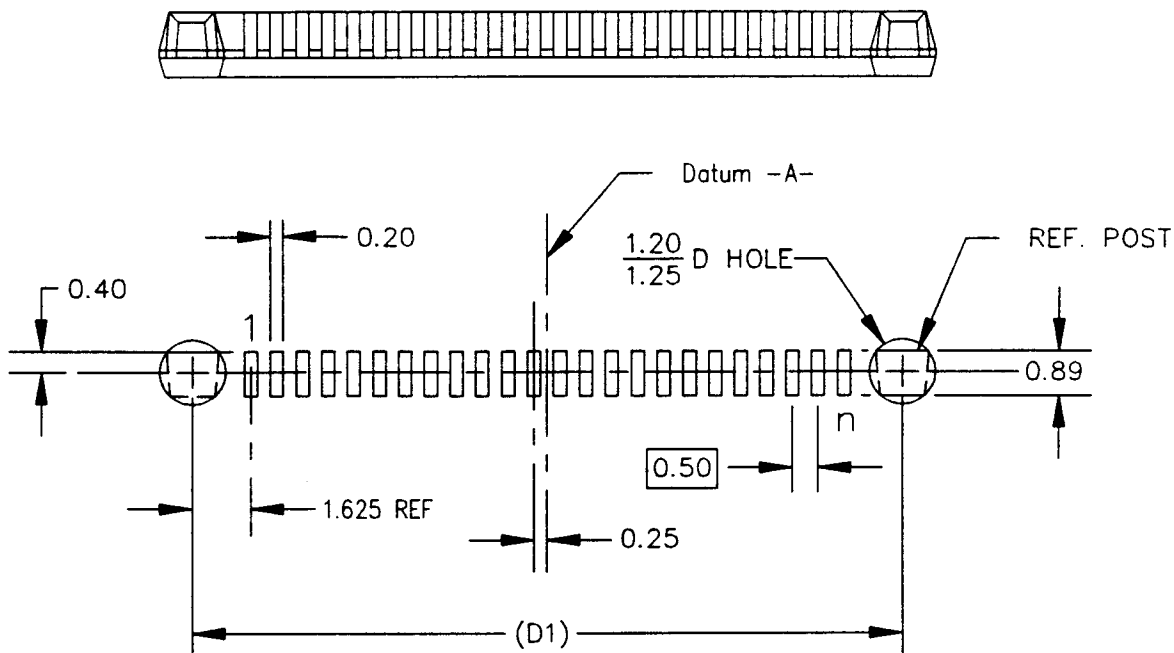


FIGURE 4

APPLICATION NOTE  
POST AND LEAD RELATIONSHIP  
(FOR REFERENCE ONLY)

JEDEC SOLID STATE PRODUCTS OUTLINES	TITLE VERTICAL SURFACE MOUNT PACKAGE 0.50 MM LEAD PITCH R-PSIP-X24	ISSUE A	DATE 3/93	ITEM MO - 141	SHEET 4 of 5
---	---	------------	--------------	------------------	-----------------

S Y M B O L S	VARIATIONS ALL DIMENSIONS IN MILLIMETERS											
	AA				AB							
	MIN.	NOM.	MAX.	NOTE	MIN.	NOM.	MAX.	NOTE	MIN.	NOM.	MAX.	NOTE
A	7.35	7.50	7.60	3	10.35	10.50	10.60	3				
A1		8.35 REF		3		11.35 REF		3				
A2	0.50	1.00	1.20	3	0.50	1.00	1.20	3				
A3	6.85	7.00	7.10	3,7	9.85	10.00	10.10	3,7				
b	0.15	0.20	0.30		0.15	0.20	0.30					
b1	0.15	—	0.30		0.15	—	0.30					
c	0.10	—	0.21		0.10	—	0.21					
c1	0.10	—	0.21		0.10	—	0.21					
D	15.95	16.00	16.05	3,8	15.95	19.00	19.05	3,8				
D1	14.70	14.75	14.80	3	14.70	14.75	14.80	3				
E	1.20	1.25	1.30		1.20	1.25	1.30					
E1	0.83	0.88	0.93		0.83	0.88	0.93					
e		0.50				0.50						
L	0.85	0.90	0.95		0.85	0.90	0.95					
N		24		4		24		4				
NOTE	1,2,5,6											
REF	11-319											
ISS												

Patented Product

## NOTES:

- 1 All dimensions and tolerances conform to ANSI Y14.5m-1982.
- 2 Datum plane -B- located at mold parting plane at the surface of the positioning posts.
- 3 Dimensions A, A1, A2, A3, D and D1 do not include mold protrusions. Allowable protrusion is 0.07 per side.
- 4 Pin numbers are for reference only.
- 5 Pin 1 identifier.
- 6 Post to exhibit interference fit into 1.20/1.25 mm $\varnothing$  hole.
- 7 Package height, A3, to be integral multiple of 1.00mm.
- 8 Package length, D, to be integral multiples of 2 x e.

JEDEC SOLID STATE PRODUCTS OUTLINES	TITLE VERTICAL SURFACE MOUNT PACKAGE 0.50 MM LEAD PITCH R-PSIP-X24	ISSUE A	DATE 3/93	ITEM MO - 141	SHEET 5 of 5
---	---	------------	--------------	------------------	-----------------